

Microelectromechanical coupling device**ABSTRACT**

The invention relates to a microelectromechanical coupling device (100) for coupling microelectromechanical components, having a flexible ring structure (110) which forms a circle in an idle state and which can be deformed substantially parallel to the plane of the circle and is suitable for coupling the microelectromechanical components (200); and a plurality of spring elements (120) which are suitable for connecting the ring structure (110) to a substrate. The coupling device (100) has such a large number of a spring elements (120), such a small width in the circumferential direction of the ring structure (110), and such a low spring hardness that the deformability of the ring structure (110) is homogenous in the circumferential direction of the ring structure (110).

(Fig. 1A)